

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
Contact Info: ti.com/support
Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
Created on: 06/04/2022

Details for "OPA2705EA/250G4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
OPA2705EA/250G4	NIPDAUAG	Level-2-260C-1 YEAR	Ext-Mfg	DGK 8	3x3x1	29.1

***Total Device Mass**
The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.031024	99.987108	999871	0.106749	1067
Not Categorized	Proprietary Materials		0.000004	0.012892	129	0.000014	0
Sub-Total			0.031028	100	1000000	0.106763	1068
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.297146	82.000039	820000	1.022434	10224
Thermoplastics	Epoxy	85954-11-6	0.065227	17.999961	180000	0.224436	2244
Sub-Total			0.362373	100	1000000	1.24687	12469
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	13.036772	99.7	997000	44.85755	448575
Magnesium and Its Alloys	Magnesium	7439-95-4	0.006538	0.05	500	0.022496	225
Other Inorganic Materials	Silicon	7440-21-3	0.03269	0.25	2500	0.112481	1125
Sub-Total			13.076	100	1000000	44.992527	449925
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.3892	97.3	973000	1.339178	13392
Precious Metals	Gold	7440-57-5	0.0012	0.3	3000	0.004129	41
Precious Metals	Palladium	7440-05-3	0.0084	2.1	21000	0.028903	289
Precious Metals	Silver	7440-22-4	0.0012	0.3	3000	0.004129	41
Sub-Total			0.4	100	1000000	1.376339	13763
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	13.121501	92.500003	925000	45.149089	451491
Other Plastics and Rubber	Carbon Black	1333-86-4	0.070927	0.5	5000	0.244049	2440
Thermoplastics	Epoxy	85954-11-6	0.992978	6.999997	70000	3.416686	34167
Sub-Total			14.185406	100	1000000	48.809824	488098
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	1.007797	100	1000000	3.467676	34677
Sub-Total			1.007797	100	1000000	3.467676	34677
Total							
			29.062604			100	1000000

Important Note
The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer
TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J57098 low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.